

ABSTRACT OF THE DISCLOSURE

A method of manufacturing an electronic circuit module includes flow soldering including preheating an interconnect substrate on which an electronic part is placed, and supplying molten solder to a first surface of the interconnect substrate, whereby the first surface is heated to a specific temperature, wherein the interconnect substrate is heated by the preheating so that a difference between a temperature of the first surface immediately before supplying the molten solder and the specific temperature at the time of supplying the molten solder is 100°C or less.